# 2SD1368

## Silicon NPN Epitaxial

# **HITACHI**

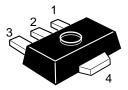
ADE-208-1148 (Z) 1st. Edition Mar. 2001

## Application

- Low frequency power amplifier
- Complementary pair with 2SB1002

#### **Outline**

**UPAK** 



- 1. Base
- 2. Collector
- 3. Emitter
- 4. Collector (Flange)



#### 2SD1368

#### **Absolute Maximum Ratings** $(Ta = 25^{\circ}C)$

Item	Symbol	Ratings	Unit
Collector to base voltage	$V_{\text{CBO}}$	100	V
Collector to emitter voltage	V <sub>CEO</sub>	50	V
Emitter to base voltage	$V_{EBO}$	6	V
Collector current	I <sub>c</sub>	1	А
Collector peak current	i <sub>C(peak)</sub> *1	1.5	А
Collector power dissipation	P <sub>C</sub> *2	1	W
Junction temperature	Tj	150	°C
Storage temperature	Tstg	-55 to +150	°C

Notes: 1. PW ≤ 10 ms, Duty cycle ≤ 20%

2. Value on the alumina ceramic board (12.5 x 20 x 0.7 mm)

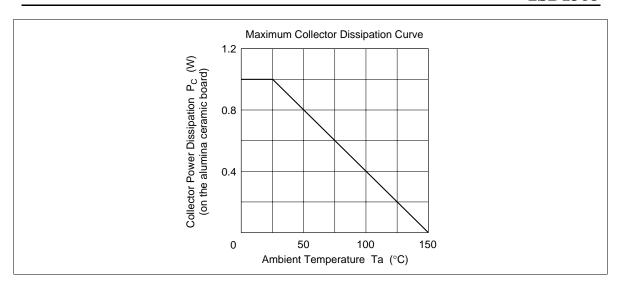
## **Electrical Characteristics** ( $Ta = 25^{\circ}C$ )

Item	Symbol	Min	Тур	Max	Unit	Test conditions
Collector to base breakdown voltage	$V_{(BR)CBO}$	100	_	_	V	$I_{c} = 10 \ \mu A, \ I_{E} = 0$
Collector to emitter breakdown voltage	$V_{(BR)CEO}$	50	_	_	V	$I_C = 1 \text{ mA}, R_{BE} = \infty$
Emitter to base breakdown voltage	$V_{(BR)EBO}$	6	_	_	V	$I_{E} = 10 \ \mu A, \ I_{C} = 0$
Collector cutoff current	I <sub>CBO</sub>	_	_	0.1	μΑ	$V_{CB} = 80 \text{ V}, I_{E} = 0$
Emitter cutoff current	I <sub>EBO</sub>	_	_	0.1	μΑ	$V_{EB} = 4 \text{ V}, I_{C} = 0$
DC current transfer ratio	h <sub>FE</sub> *1	100	_	500		$V_{CE} = 2 \text{ V}, I_{C} = 0.1 \text{ A}$
Collector to emitter saturation voltage	$V_{\text{CE(sat)}}$	_	_	0.3	V	I <sub>C</sub> = 1 A, I <sub>B</sub> = 0.1 A, Pulse
Base to emitter saturation voltage	$V_{BE(sat)}$	_	_	1.2	V	I <sub>C</sub> = 1 A, I <sub>B</sub> = 0.1 A, Pulse
Gain bandwidth product	f <sub>T</sub>	_	100	_	MHz	$V_{CE} = 2 \text{ V}, I_{C} = 10 \text{ mA}, \text{ Pulse}$
Collector output capacitance	Cob	_	20	_	pF	$V_{CB} = 10 \text{ V}, I_{E} = 0, f = 1 \text{ MHz}$

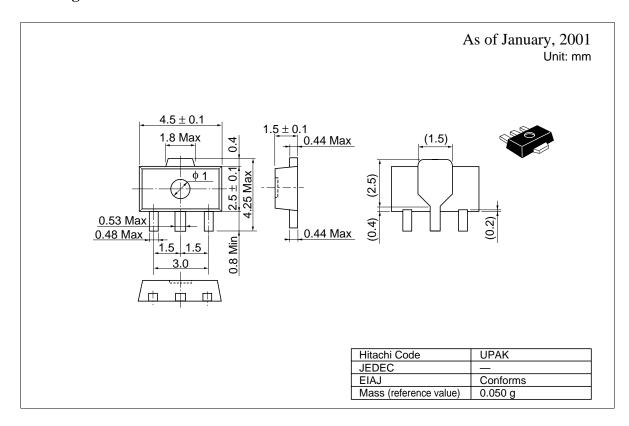
Note: 1. The 2SD1368 is grouped by  $h_{\text{FE}}$  as follows.

Mark	CA	СВ	CC
h <sub>FE</sub>	100 to 200	160 to 320	250 to 500

See characteristic curves of 2SD789.



## **Package Dimensions**



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# IITACE

Semiconductor & Integrated Circuits.

Nippon Bldg., 2-6-2, Ohte-machi, Chiyoda-ku, Tokyo 100-0004, Japan

Tel: Tokyo (03) 3270-2111 Fax: (03) 3270-5109

URL NorthAmerica : http://semiconductor.hitachi.com/ Europe http://www.hitachi-eu.com/hel/ecg Asia http://sicapac.hitachi-asia.com Japan http://www.hitachi.co.jp/Sicd/indx.htm

#### For further information write to:

Hitachi Semiconductor (America) Inc. 179 East Tasman Drive, San Jose,CA 95134 Tel: <1> (408) 433-1990 Germany

Hitachi Europe GmbH Electronic Components Group Dornacher Straße 3 D-85622 Feldkirchen, Munich Fax: <1>(408) 433-0223 Tel: <49> (89) 9 9180-0 Fax: <49> (89) 9 29 30 00

> Hitachi Europe Ltd. Electronic Components Group. Whitebrook Park Lower Cookham Road Maidenhead Berkshire SL6 8YA, United Kingdom Tel: <886>-(2)-2718-3666 Tel: <44> (1628) 585000 Fax: <44> (1628) 585160

Hitachi Asia Ltd. Hitachi Tower 16 Collyer Quay #20-00, Singapore 049318 Tel: <65>-538-6533/538-8577

Fax: <65>-538-6933/538-3877 URL: http://www.hitachi.com.sg

Hitachi Asia Ltd (Taipei Branch Office) 4/F, No. 167, Tun Hwa North Road, Hung-Kuo Building. Taipei (105), Taiwan

Fax: <886>-(2)-2718-8180 Telex: 23222 HAS-TP URL: http://www.hitachi.com.tw Hitachi Asia (Hong Kong) Ltd. Group III (Electronic Components) 7/F., North Tower, World Finance Centre, Harbour City, Canton Road Tsim Sha Tsui, Kowloon, Hong Kong

Tel: <852>-(2)-735-9218 Fax: <852>-(2)-730-0281 URL: http://www.hitachi.com.hk

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